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### **N-Channel 30V Fast Switching MOSFET**

### **General Description**

The QN3106M6N is a high performance trench N-channel MOSFET which utilizes extremely high cell density to provide low Rdson and gate charge characteristics. It is ideally suited to support synchronous buck converter applications.

The QN3106M6N meets RoHS and Green Product requirements while supporting full function reliability.

#### **Features**

- ✓ Advanced high cell density Trench technology
- ✓ Super Low Gate Charge
- ✓ Green Device Available

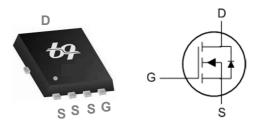
### **Product Summary**

V <sub>DS</sub>	R <sub>DS(ON)</sub> max (V <sub>GS</sub> =10V)	I <sub>D</sub> (T <sub>C</sub> =25 °C)
30V	3.8mΩ	90A

#### **Applications**

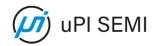
- ✓ High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- ✓ Networking DC-DC Power System
- ✓ Load Switch

#### **Pin Configuration**



### **Ordering Information**

Order Number	Package Type	Top Marking		
QN3106M6N	PRPAK5X6	Weekly Code Yearly Code Logo Pin 1 dot Sequence  Assembly Code		



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	90	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	57	А
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	18	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	14	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	180	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	84	mJ
I <sub>AS</sub>	Avalanche Current	41	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	48	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

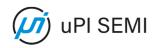
### **Thermal Data**

Symbol	Parameter		Max.	Unit	
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		62	°C/W	
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		2.6	°C/W	



### **N-Channel Electrical Characteristics**

N-Channel Electrical Characteristics: (T <sub>J</sub> =25 °ℂ, unless otherwise noted)							
Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30			V	
△BV <sub>DSS</sub> /△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA		0.01		V/°C	
BV <sub>DSSt</sub>	Drain-Source Breakdown Voltage (transient)	$V_{GS} = 0 \text{ V}, I_{D(aval)} = 12.6 \text{ A},$ $T_{case} = 25^{\circ}\text{C}, t_{transient} = 100 \text{ ns}$	34			V	
D	Static Drain-Source	V <sub>GS</sub> =10V, I <sub>D</sub> =30A		3.0	3.8		
$R_{DS(ON)}$	On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A		4.5	5.9	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/   -250uA	1.2		2.5	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-4.8		mV/°C	
1	Drain Course Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V,T <sub>J</sub> =25°C			1		
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V,T <sub>J</sub> =55°C			5	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =15A		32		S	
$R_g$	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz		1.5		Ω	
$Q_g$	Total Gate Charge (10V)	V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =15A		19.9			
$Q_g$	Total Gate Charge (4.5V)			9.6			
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A		3.8		nC	
$Q_{gd}$	Gate-Drain Charge			3.6			
t <sub>d(on)</sub>	Turn-On Delay Time			8.9			
t <sub>r</sub>	Rise Time	$V_{DS}$ =15V, $V_{GS}$ =10V, $R_{G}$ =3.3 $\Omega$ ,		44.7			
$t_{d(off)}$	Turn-Off Delay Time	I <sub>D</sub> =15A		18.5		ns	
t <sub>f</sub>	Fall Time			4.6			
C <sub>iss</sub>	Input Capacitance			1146			
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz		697		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			33			



### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =29A	42.05	1	-	mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current 1,6	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current			90	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				180	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =15A, di/dt=100A/μs,		38.4		nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25℃		26.3		nC

#### Note:

- 1. Test data conducted with surface mount attachment to 1 inch<sup>2</sup>, FR-4 board utilizing 2oz copper
- 2. Pulse Test. Pulse width  $\leq$  300uS, duty cycle  $\leq$  2%
- 3. EAS data is a maximum rating. The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH
- 4. The power dissipation is limited by a 150°C maximum junction temperature
- 5. The Min. value is 100% EAS tested guarantee
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ . In real applications, it will be limited by total power



### **Typical Characteristics**

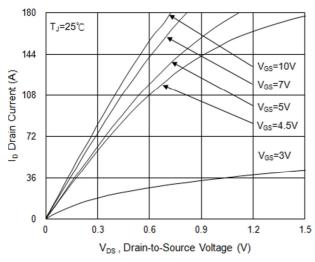


Fig.1: Typical Output Characteristics

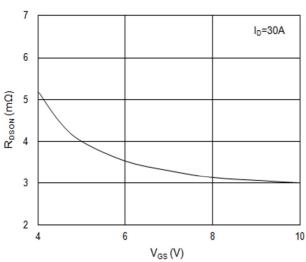


Fig.3: On-Resistance vs. Gate-Source

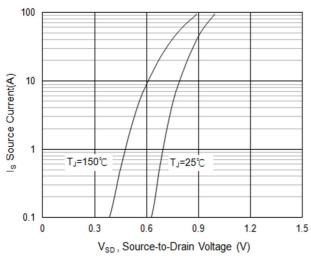


Fig.5: Forward Characteristics of Reverse

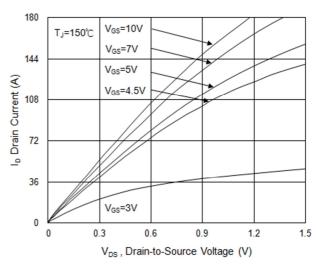


Fig.2: Typical Output Characteristics

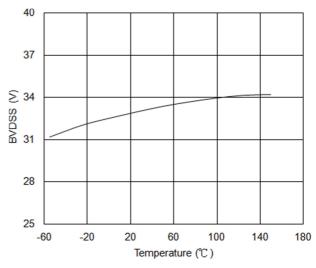


Fig.4: Drain-Source Breakdown Voltage

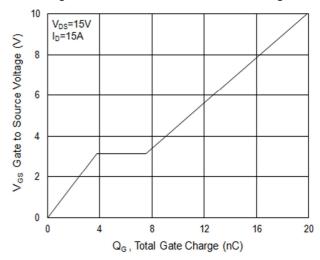


Fig.6: Gate-Charge Characteristics



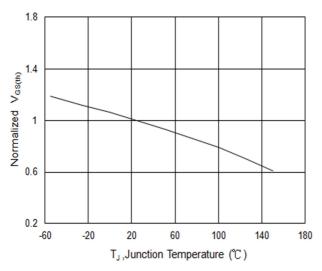


Fig.7: Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

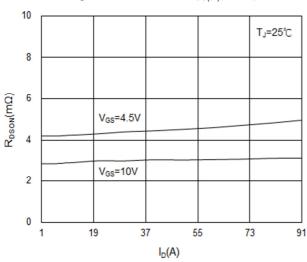


Fig.9: Drain-Source On-State Resistance

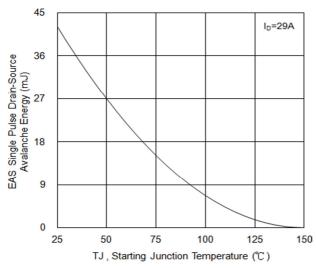


Fig.11: Single Pulse Avalanche Energy

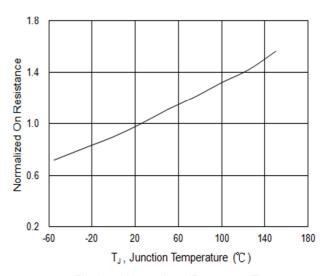


Fig.8: Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

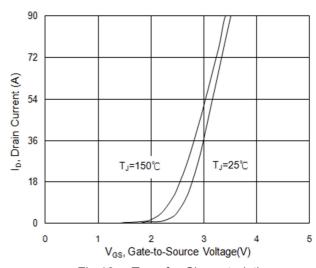


Fig.10: Transfer Characteristics

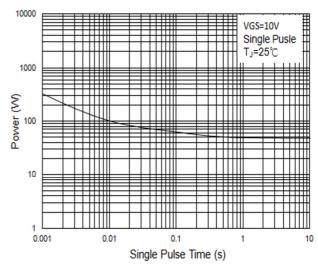


Fig.12: Single Pulse Maximum Power Dissipation



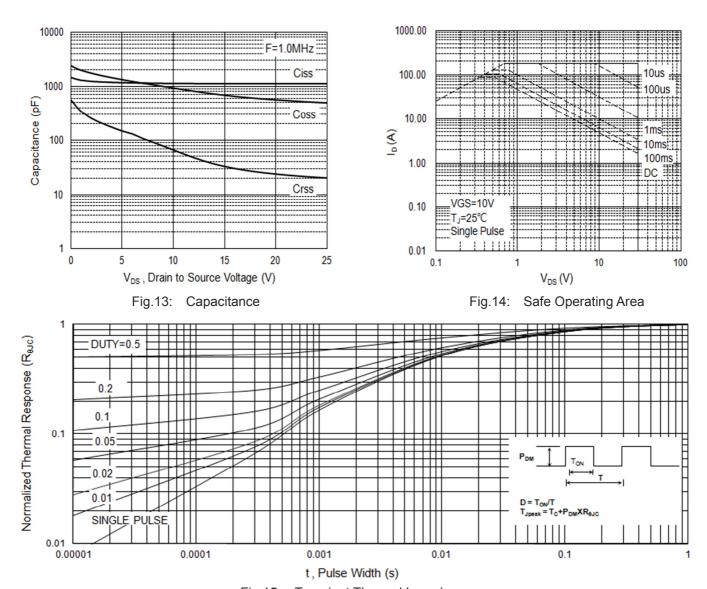


Fig.15: Transient Thermal Impedance



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